Information for Prospective Corporate Supporters

2017 European Test Symposium Corporate Support Opportunity "At a Glance"

- ETS is the annual premier European event totally devoted to test and test-synthesis of micro-electronic circuits and systems, attracting around 200 industrial and academic professionals from around the world.
- ETS traditionally enjoys a strong balance among academic and industrial participants.
- ETS 2017 will be held in Limassol, Cyprus, from May 22–26, 2017.
- Your company is invited to support ETS'17 at Bronze (€1500), Silver (€2500), Gold (€5000) or Platinum (€8000) level.
- The money will be used solely to cover the costs associated with ETS, thereby attracting yet more attendees.
- In return: company logo on ETS web site, poster, and printed program; advertising space in the program booklet; advertisement e-mail to registered participants (support level Silver and up); display of company logos during session intervals; opportunity to provide company hand-out material; priority in the selection process for the Vendor Sessions and/or Table-Top Demos; and more…
- ETS corporate supporters in recent years: Advantest, Alter, ARM, Arques, Arrow, ASML, Atmel, Bosch, Cadence Design Systems, Cascade Microtech, Cisco Systems, DeFacTo Technologies, Elektronikk, Eles, Forskningsraadet, Freescale Semiconductor, Göpel Electronic GmbH, Honeywell, Infineon Technologies, Intel, iROC, JEM, JTAG Technologies, Mentor Graphics, Micronas, Nordic Semiconductor, NXP Semiconductors, Optimal+, Pintail Technologies, Preciosa, Presto Engineering, Q-Star Test, Qualcomm, Qualtera, Ridgetop Group, Salland Engineering, Spea, STC, STMicroelectronics, Synopsys, SynTest, Technoprobe, TEL, Temento, Teradyne, TestAdvantage, TestInsight, Verigy, VSystems, XJTAG, etc.

About ETS'17 – http://www.ets17.org.cy

As you probably know, the IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, applications, hot topics, and new trends in the area of electronic-based circuits and system testing and reliability. ETS is organized annually in a different European country. In 2017, ETS will be held in Limassol, Cyprus, and will take place during May 22-26.

ETS is the major event of the European Test Week that includes TSS (Test Spring School) and fringe workshops. The ETS program comprises plenary keynotes, parallel paper sessions, vendor sessions and table-top demos, poster sessions, embedded tutorial sessions, panel sessions, and an industry-driven special track on Emerging Test Strategies (ETS^2) presenting new issues which are discussed in an informal atmosphere. This year, ETS introduces the new initiative of Industry Wish List, where industry presents elevator talks on open issues that demand urgent solutions.

ETS is renowned for its excellent Social Event and informal atmosphere, providing many opportunities for networking. ETS is annually attended by many design, design-for-test, and test and reliability professionals from companies and academia.

Corporate Support ETS'17

Every year, ETS is financially supported by a number of companies, both large multi-national corporations as well as smaller SMEs. Their donation is solely used to cover costs associated with ETS and make the event accessible to even more attendees. In return, ETS gives the supporting company various benefits, as explained below.

ETS has defined four different support grades, each with different support amounts and different benefits.

1. **Bronze**: *€1500*
   - Supporter's name and logo will appear in the symposium's web page, the symposium posters, and the printed programs that will be distributed to the participants.
   - *Half-page* advertising space in the program booklet for the event. The Advance Program will be available as a downloadable PDF document before the event, and the Final Program will be a hard-copy booklet handed out to all registered attendees.
   - Priority in slot assignment for the Vendor Sessions.
   - Constant exposure of company logo in a repeating presentation loop before, in-between, and after sessions.
   - The supporter will be allowed to provide branded give-away items for inclusion in the symposium registration bag.

2. **Silver**: *€2500*
   - As per Bronze Level, plus:
   - *Full-page* advertising space in the program booklet.
   - The supporter's name and logo will appear in the proceedings of the symposium.
   - The supporter's name and logo will appear on the symposium's registration bag.
   - Opportunity to send out *one advertisement* e-mail to registered symposium participants prior to the symposium.

3. **Gold**: *€5000*
   - As per Silver Level, plus:
   - A special area and/or Table Top Demo at the symposium site will be assigned to the supporter as its own demonstration area (posters, leaflets, recruitment material, and other advertisement material). This could be a table (provided by ETS) or a booth (supplied by the corporate supporter).
   - Opportunity to send out *two advertisement* e-mails to registered symposium participants prior to the symposium.

4. **Platinum**: *At least €8000*
   - This is a Main Corporate Supporter. As per Gold Level, plus:
   - *Guaranteed* slot assignment in the Vendor Sessions.
   - The support money will be used primarily for the Social Event of the workshop, which will be announced "to be offered by the Main Supporter(s)".
   - Additional publicity paths can be arranged as requested by the supporter.

All four support grades can be augmented with a **Plus** option: for €500 extra, one of the supporter's employees gets a full ETS'17 registration.

Vendor Session Presentations

ETS offers commercial vendors the opportunity to give technical presentations in Vendor Sessions in a track parallel to the regular paper sessions. Typical content could include technical descriptions, case studies, best practices, and user testimonials of products or solutions. These presentations will be listed in the symposium program along with the other sessions, and should be targeted to ETS' technical audience. Vendor Sessions differ from other ETS presentations in that company names, logos, and product names may be mentioned explicitly. Proposal selection is based on technical content and relevance to ETS audience and topics. Vendor Session slots will be assigned in a first-come-first-served order, but priority will be given to Corporate Supporters with higher priority for higher support grades.

Table Top Demos

ETS offers the opportunity to present Table-Top Demos during the event. Table-Top Demo participants get a table, poster board, and electricity outlet provided by ETS. A Table-Top Demo presentation may include displaying slides and/or demoing tools or products. Typical content is comprised of technical descriptions, case studies, best practices, and user testimonials of products or solutions and should be targeted to the ETS' technical audience. Table Top Demos will be listed in the symposium program as well. Proposal selection is based on technical content and relevance to ETS audience and topics. Table-Top Demo tables will be assigned in a first-come-first-served order, but priority will be given to Corporate Supporters with higher priority for higher support grades.

Next Steps

We invite your company to become a corporate supporter of ETS'17 and contribute to a successful event! Your presence at the symposium will give you an excellent opportunity to network with established and new design, test, and reliability engineers and their managers.

If your company is interested in taking advantage of this opportunity, ETS'17 will draft a small contract, with the details of the deal and information regarding money transfer. Also, we will need a high-resolution electronic version of your company logo, as well as advertisement material for the program booklet.

Naturally, we would be happy to discuss with you any ideas you have to make this opportunity even more fruitful for your company. We hope to hear from you soon.

Best regards,

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Tips to Get The Most Out of Your ETS'17 Corporate Support

- Select your support level: Bronze (€1500), Silver (€2500), Gold (€5000), or Platinum (€8000).
- Note that level Silver and up entitle you to an e-mail broadcast to all registered ETS participants prior to the symposium: a great way to inform them about your affiliation with the event.
- Upgrade your support level with the Plus option: for €500, you can have someone participating in the symposium at the discount price of early registration rate for IEEE members (even if you are late or not IEEE member). Your support will become so much more valuable with someone personally present at the event that (potential) customers can talk to.
- Submit a proposal for a Vendor Session presentation and/or Table-Top Demo. This will allow you to present your company and its products to ETS' highly-targeted audience.

Affiliations of Past ETS Attendees

ABB
Advantest
Aix-Marseille Universite
Alcatel-Lucent
Alcatel-Lucent Bell Labs
AMD
Analog Devices
Apache Design
Applus
Aptasic
Aptina Imaging
ARM
ARQES
Aster Technologies
ASU
Atmel
Atrenta
Auburn University
austria micro systems
Bar-Ilan University
Bielefeld University
Bilkent University
Blue Pearl Software
Boston Scientific
Brandenburgische TU Cottbus
Brno University of Technology
Cadence Design Systems
Carlos III University of Madrid
Cassidian CyberSecurity
Catholic University - PUCRS
CEA-LETI
Chalmers University of Technology
Chinese University of Hong Kong
Cisco Systems
CMP
CNM
CNRS
Continental Automotive
CSEM
Czech Technical University
Data Respons Norge
DeFacTo Technologies
Delft University of Technology
DFKI
Dialog Semiconductor
DOCEA Power
DTU
Duke University
EADS
Ehime University
EIS by Semcon
Elmos Semiconductor
EPFL
Ericsson
ETRI
Fraunhofer IIS
Freescale Semiconductor
Fukuoka Institute of Technology
Futurewei Technologies
Gemalto
Georgia Institute of Technology
German Aerospace Center
German Aerospace Institute
Glasgow University
GlobalFoundries
GOEPEL Electronic
Graz University of Technology
Grenoble Institute of Technology
HDC
Hefei University of Technology
Hiroshima City University
HSHL University of Applied Sciences
Huawei Technologies
IBM
IIT Madras
IMEC
INAF
INESC

Infineon Technologies
Inria Grenoble
Institut fuer Technische Informatik
Intel
Intel Mobile Communications
IPA
iRoC Technologies
ITRI
JAIST
Jozef Stefan Institute
JTAG Technologies
Karlsruhe Institute of Technology
Kozio
KTH Stockholm
KU Leuven
Kyushu Institute of Technology
Lab-STICC
Lancaster University
Lattice Semiconductor
Linköping University
LIRMM
LTX-Credence
Lund University
Marvell
McGill University
McMaster University
Melexis
Mentor Graphics
Nara Institute of Science and Technology
National Central University
National Instruments
National Sun Yat-sen University
National Taiwan University
National Tsing Hua University
New York University
New York University Abu Dhabi
New York University- Poly
Newcastle University
Nihon University
Nordic Semiconductor
Norwegian Univ. of Science and Technology
NSRI
NXP Semiconductors
OFFIS
Osaka University
PDF Solutions
Politecnico di Milano
Politecnico di Torino
Politehnica University of Timisoara
Polytechnic Institute of New York University
Poznan University of Technology
Presto Engineering
priscaspian
Purdue University
Qualtera
Radboud University Nijmegen
RAFAEL
ReSeCo
Ridgetop Europe
Ridgetop Group
Robert Bosch
Ruppin Academic Center
Russian Academy of Science
RWTH Aachen University
Salland Engineering
Semcon Caran AB
Slovak University of Technology Bratislava
Soflab Technology
Sogang University
Southern Methodist University
Spintec Laboratory
ST Ericsson
ST Microelectronics
Stanford University
Tallinn University of Technology
Technical University of Cluj-Napoca
Technical University of Denmark
Technical University of Kosice

TEI of Athens
Testonica Lab
Thales
TIMA Laboratory
TNO
TOBB University of Economics and Technology
Tokyo Metropolitan University
Toltim Electrical Engineering
Tomsk State University
TSMC
TU Chemnitz
TU Darmstadt
TU Dortmund
TU Dresden
TU Kaiserslautern
TU Liberec
TU Munich
UIUC
Universidad Antonio de Nebrija
Universidad de Cantabria
Universidade Federal do Rio Grande do Sul
Universitat Autunoma de Barcelona
Universitat Politècnica de Catalunya
Universite Jean Monnet
UniversitÈ Pierre et Marie Curie
Universiti Teknologi Petronas
University Antonio de Nebrija
University College Dublin
University of Alberta
University of Athens
University of Augsburg
University of Bologna
University of Bremen
University of Cantabria
University of Cyprus
University of Erlangen-Nurnberg
University of Freiburg
University of Ioannina
University of Iowa
University of Kaiserslautern
University of Louisiana at Lafayette
University of Lund
University of Malta
University of Manchester
University of Michigan
University of Montpellier
University of Nicosia
University of Novi Sad
University of Oulu
University of Paderborn
University of Passau
University of Piraeus
University of Pisa
University of Rome Tor Vergata
University of Sevilla
University of Siegen
University of South Florida
University of Southampton
University of Stuttgart
University of Tehran
University of Texas at Austin
University of Texas at Dallas
University of Tokyo
University of Tuebingen
University of Turku
University of Twente
University of Verona
University of Vigo
Verigy
Vienna University of Technology
Virginia Tech
Waseda University
Xilinx
Yale University
Yogitech